

**Version with Markings to Show Changes Made**

Claims 11 and 19 have been amended as outlined below, and new claims 23-32 have been added. The currently pending claims, including the aforementioned amendments, are as follows:

1           11. (Once Amended) An assembly comprising:

2                   a circuit board;

3                   an area array bonding site on a surface of the circuit board; and

4                   a protective cover overlaying the bonding site, the protective cover being non-  
5                   conductive throughout at least a region thereof that overlays the bonding site, and the  
6                   protective cover removably registered to the bonding site by a plurality of posts secured to  
7                   one of the protective cover and the circuit board into a plurality of apertures disposed in  
8                   the other of the protective cover and the circuit board.

1           12.    The assembly of claim 11, wherein the protective cover includes an adhesiveless  
2                   surface contacting the bonding site.

1           19. (Once Amended) A cover for protecting an area array bonding site on a surface of a  
2                   circuit board, the circuit board having a plurality of apertures, the cover comprising:

3                   a base member having a first face and second face, the base member shaped to at  
4                   least correspond to said area array bonding site, and the base member being non-  
5                   conductive throughout at least a region thereof that is configured to overlay the bonding  
6                   site; and

7                   a plurality of posts coupled to the first face and registered for said plurality of  
8                   apertures.

1           20.    The cover of claim 19, wherein the first face of the base member further includes  
2                   a recess corresponding to said area array bonding site.

- 1           21.     The cover of claim 19, further comprising:  
2                   a graspable extension coupled to the second face of the base member.
- 1           22.     The cover of claim 19, wherein each of the plurality of posts includes a diametral  
2     slot.
- 1           23. (New Claim) The assembly of claim 11, wherein the plurality of posts are secured to  
2     the protective cover, and wherein the plurality of apertures are disposed in the circuit board.
- 1           24. (New Claim) The assembly of claim 11, wherein the protective cover is formed of a  
2     non-conductive material.
- 1           25. (New Claim) The assembly of claim 24, wherein the protective cover is formed of  
2     epoxy glass.
- 1           26. (New Claim) The assembly of claim 11, further comprising a graspable extension  
2     disposed on a surface of the protective cover opposite that which overlays the bonding site.
- 1           27. (New Claim) The assembly of claim 11, wherein each of the plurality of posts  
2     includes a diametral slot.
- 1           28. (New Claim) The assembly of claim 11, wherein the protective cover has a thickness  
2     of about 0.006 to about 0.008 inches.
- 1           29. (New Claim) The assembly of claim 11, wherein the protective cover further includes  
2     a recess overlaying the bonding site.

1           30. (New Claim) The cover of claim 19, wherein the base member is formed of a non-  
2   conductive material.

1           31. (New Claim) The cover of claim 30, wherein the base member is formed of epoxy  
2   glass.

1           32.(New Claim) The cover of claim 19, wherein the base member has a thickness of  
2   about 0.006 to about 0.008 inches.